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(12) **United States Design Patent**
Tsai et al.

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(45) **Date of Patent:** ** **Jun. 19, 2012**

(54) **SOLDER DOT FOR CIRCUIT BOARD**

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(**) Term: **14 Years**

(21) Appl. No.: **29/366,691**

(22) Filed: **Jul. 29, 2010**

Related U.S. Application Data

(63) Continuation-in-part of application No. 29/295,946, filed on Oct. 11, 2007, now abandoned.

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** .... D13/182; D8/399; 257/786; 361/760, 801, 808; 411/171; 428/576; 174/138 G

See application file for complete search history.

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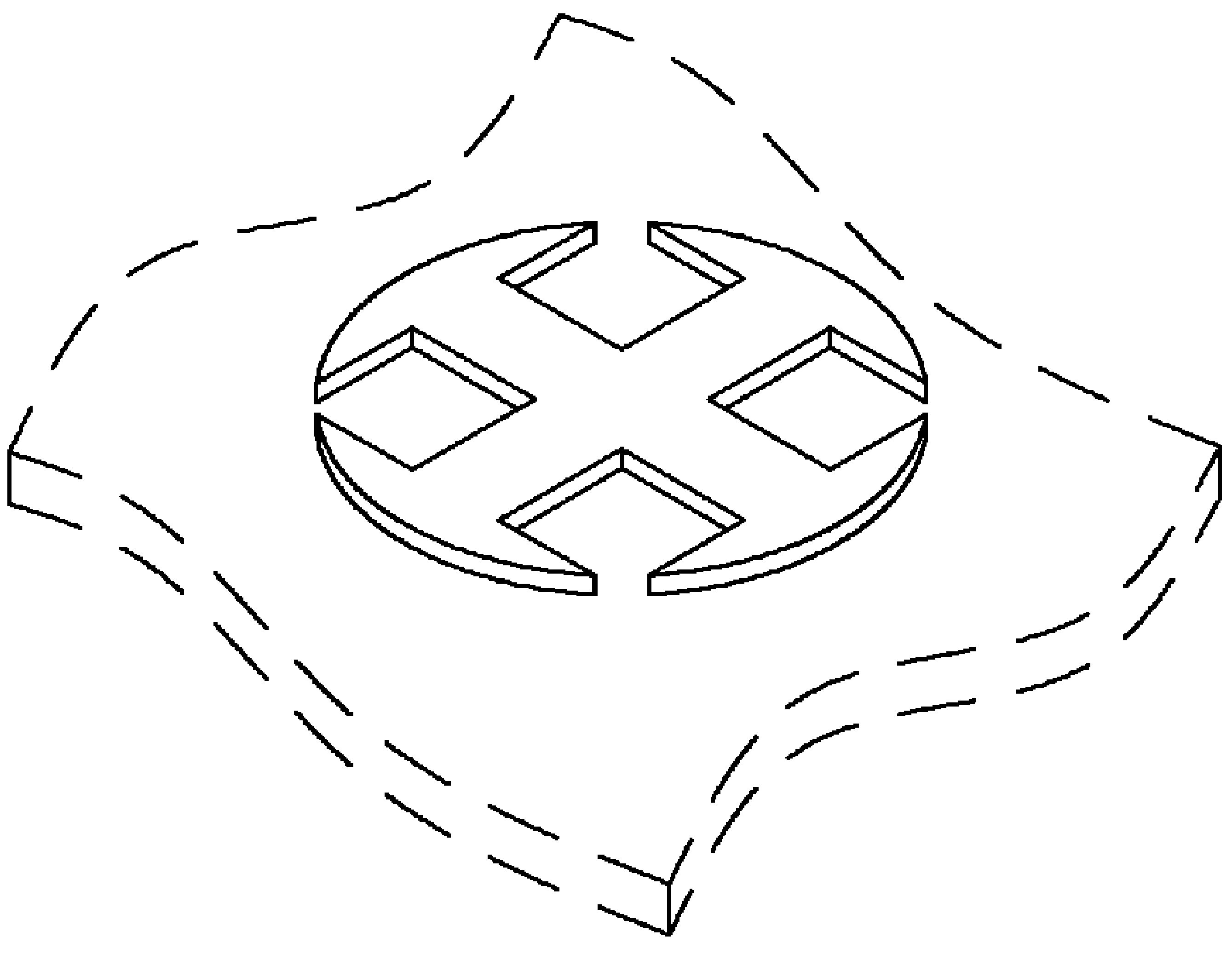
(57) **CLAIM**

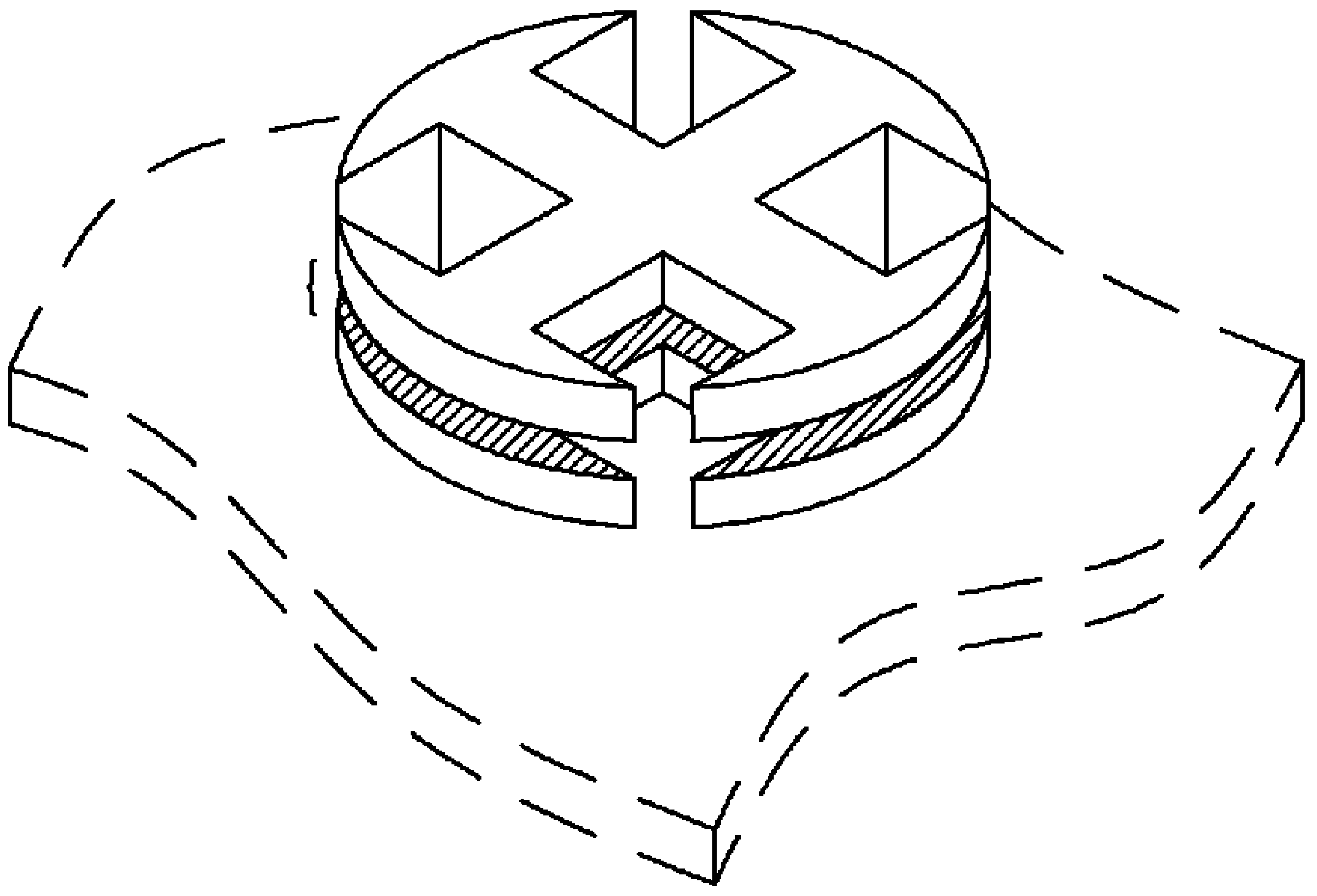
The ornamental design for a solder dot for circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of one embodiment of a solder dot for circuit board showing our new design;
FIG. **2** is a plan view thereof;
FIG. **3** is a left side elevational view thereof the right, front and rear elevation views being identical to the left side;
FIG. **4** is a perspective view of another embodiment of a solder dot for circuit board showing our new design;
FIG. **5** is a plan view thereof;
FIG. **6** is a left side elevational view thereof.
FIG. **7** is a perspective view of a solder dot for circuit board showing our new design shown in an alternate environment;
FIG. **8** is a plan view thereof;
FIG. **9** is a left side elevational view thereof the right, front and rear elevation views being identical to the left side.
FIG. **10** is a perspective view of a solder dot for circuit board showing our new design shown in an alternate environment;
FIG. **11** is a plan view thereof; and,
FIG. **12** is a left side elevational view thereof the right, front and rear elevation views being identical to the left side.
The solder dot is shown broken away in FIGS. **4**, **6**,**10**, and **12** of the drawing to indicated indeterminate length, it being understood that it has a uniform shape and appearance through its length.
The left side elevational view of one embodiment of the solder dot for circuit board is the same with a right side elevational view, a front elevational view, and a rear elevational view thereof, therefore, they are not shown. The left side elevational views of the another embodiments of the solder dot for circuit board are the same with a corresponding right side elevational view, a corresponding front elevational view, and a corresponding rear elevational view thereof, therefore, they are not shown. The broken lines showing are for illustrative purposes only and forms no part of the claimed design.

1 Claim, 12 Drawing Sheets





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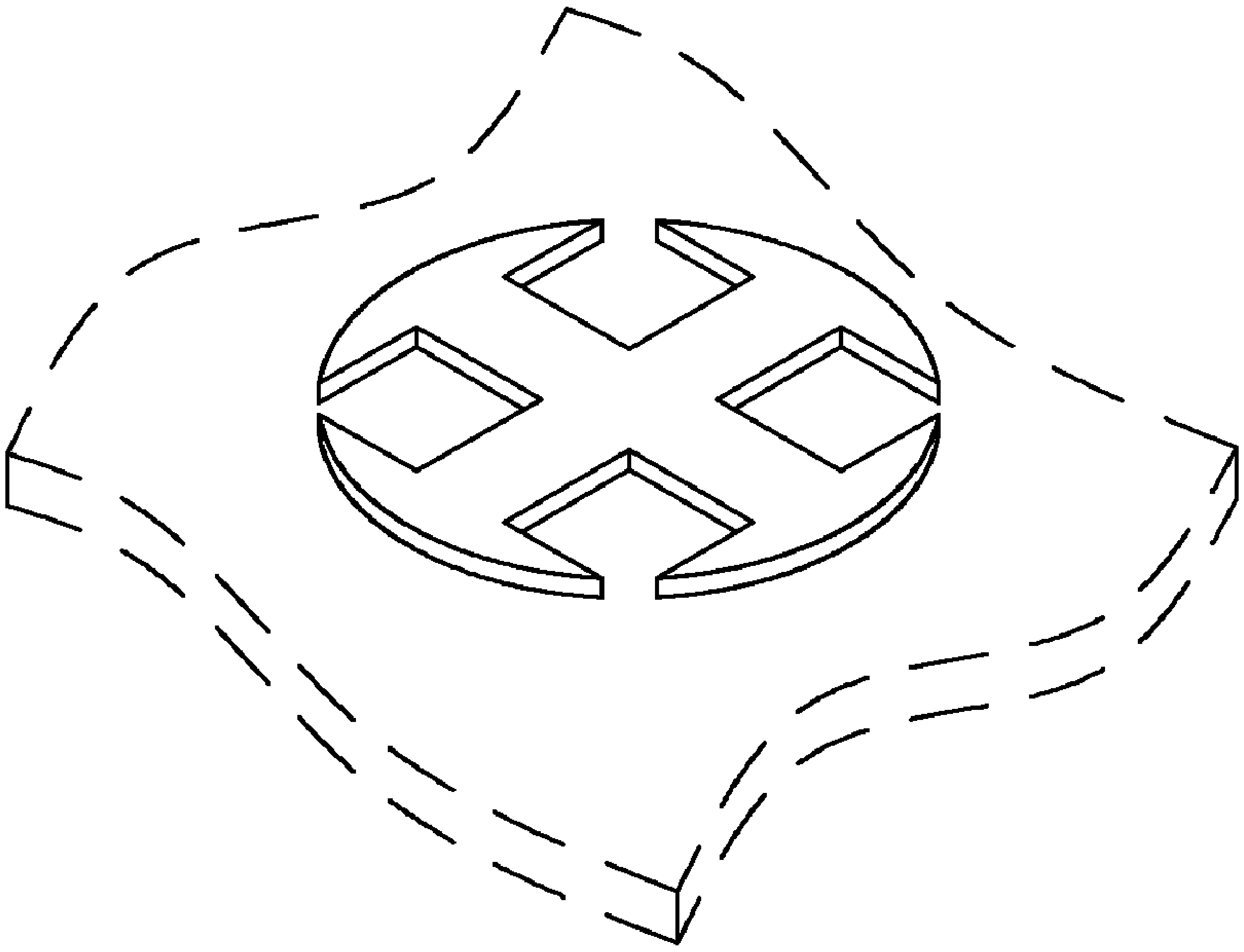

FIG. 1

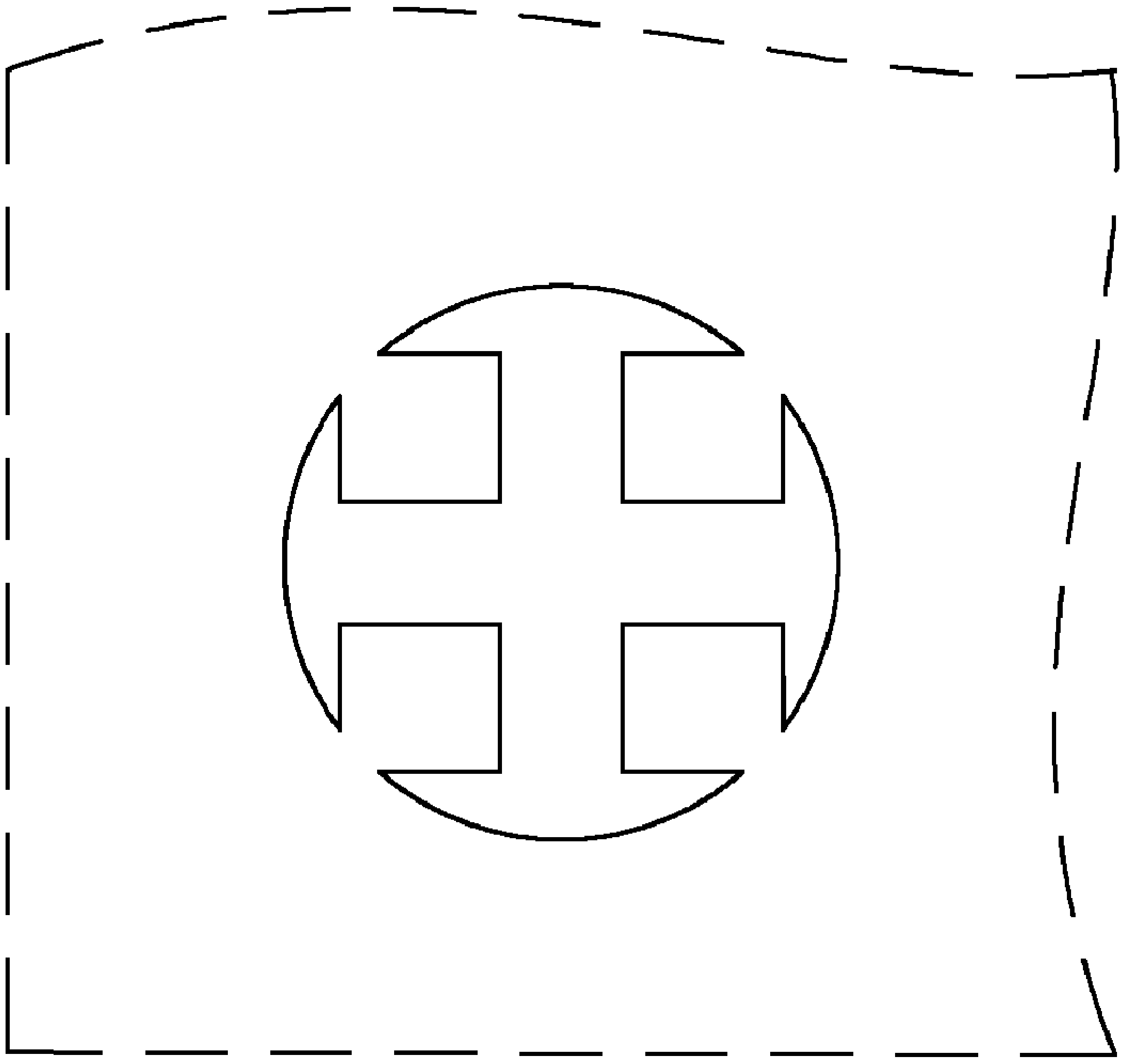

FIG. 2

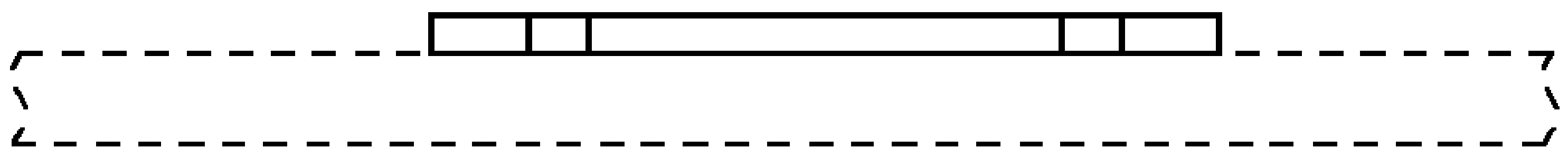

FIG. 3

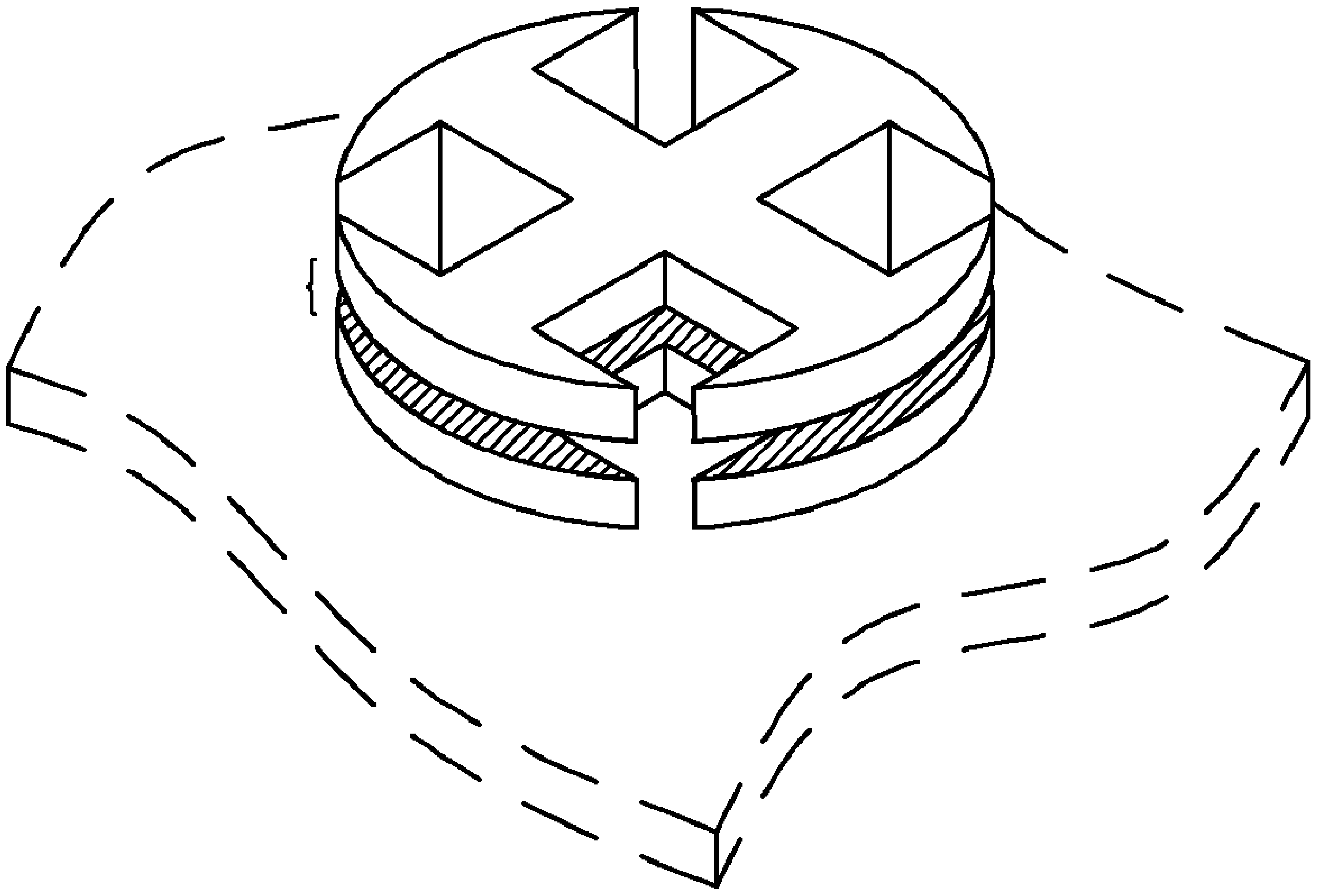

FIG. 4

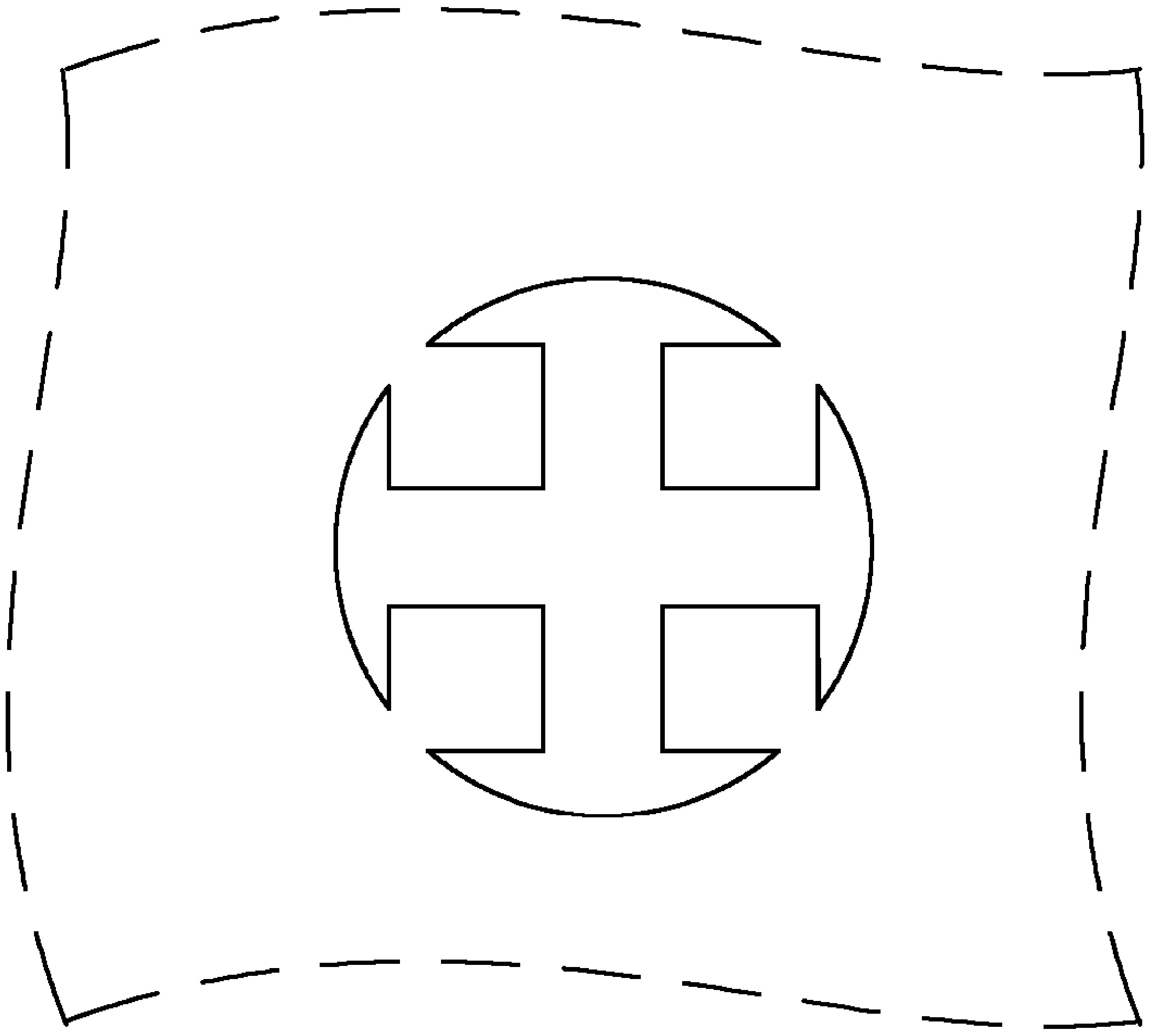

FIG. 5

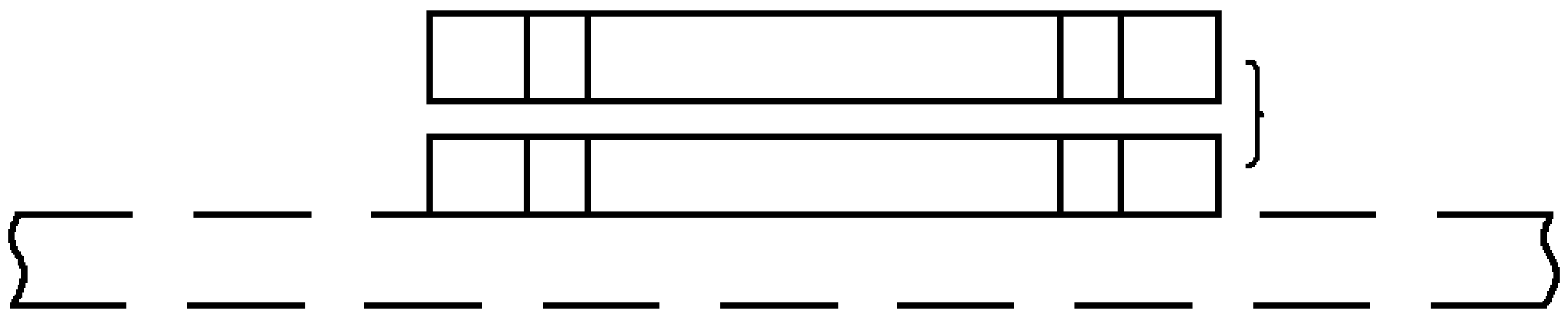

FIG. 6

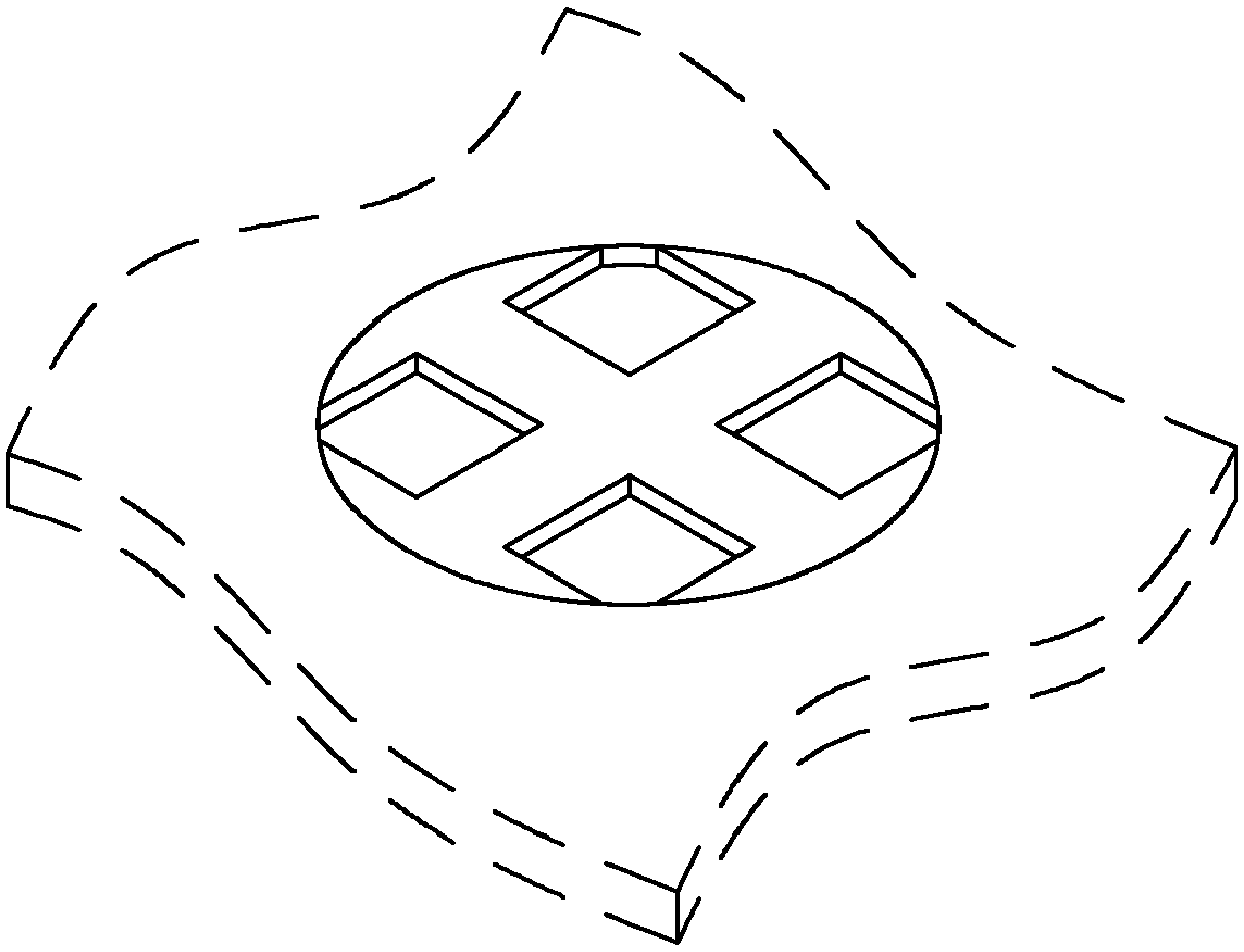

FIG. 7

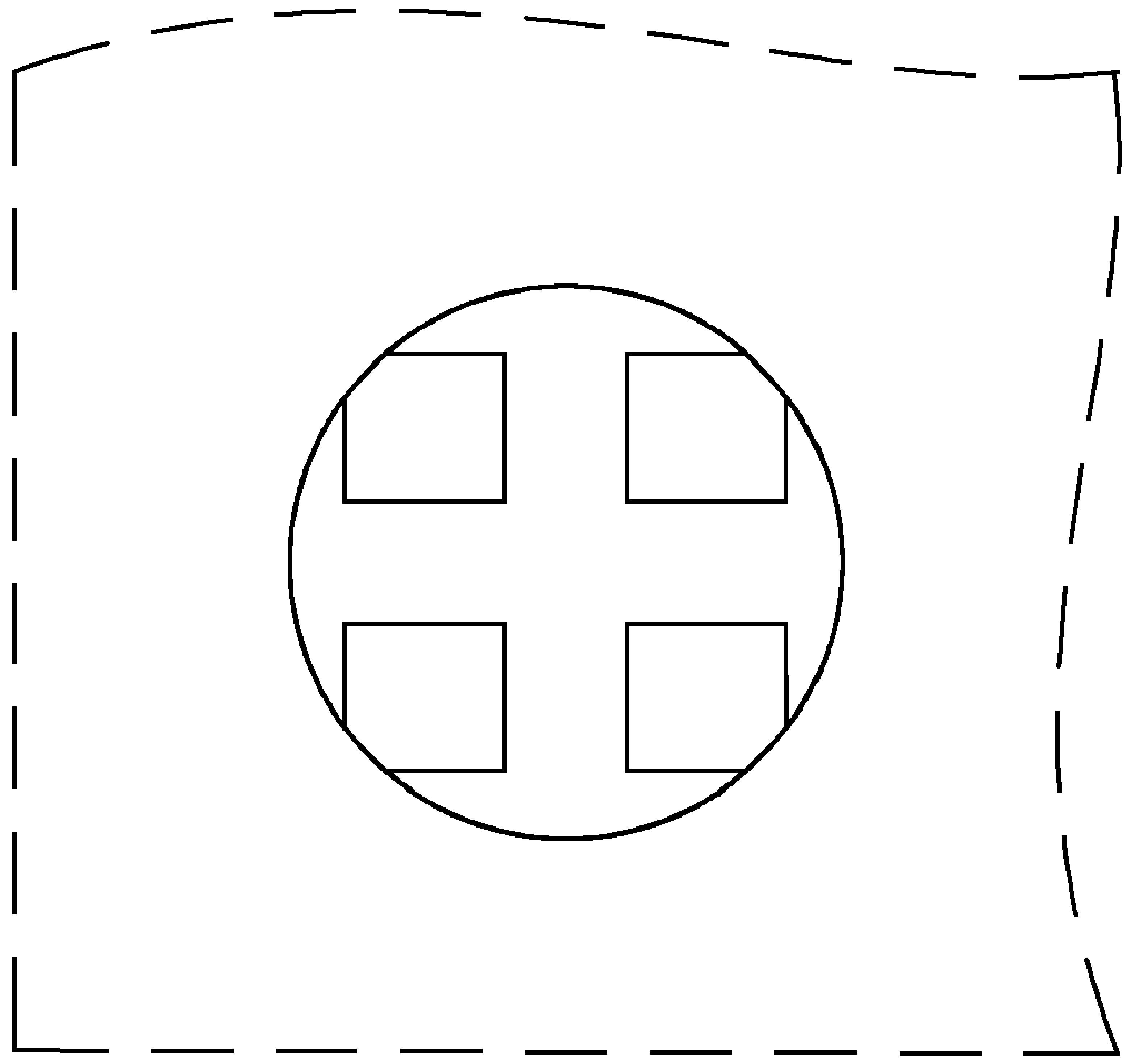

FIG. 8

FIG. 9

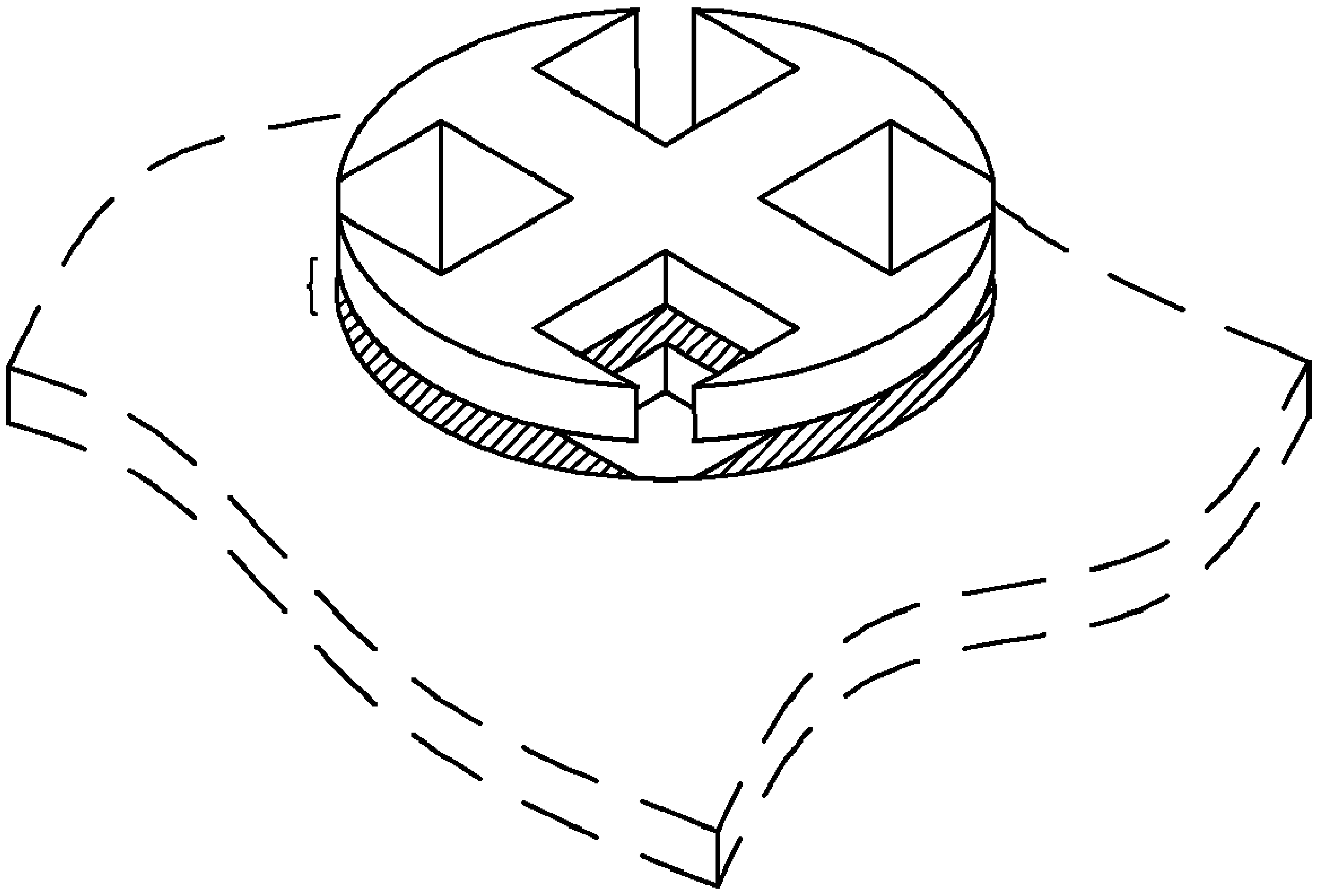

FIG. 10

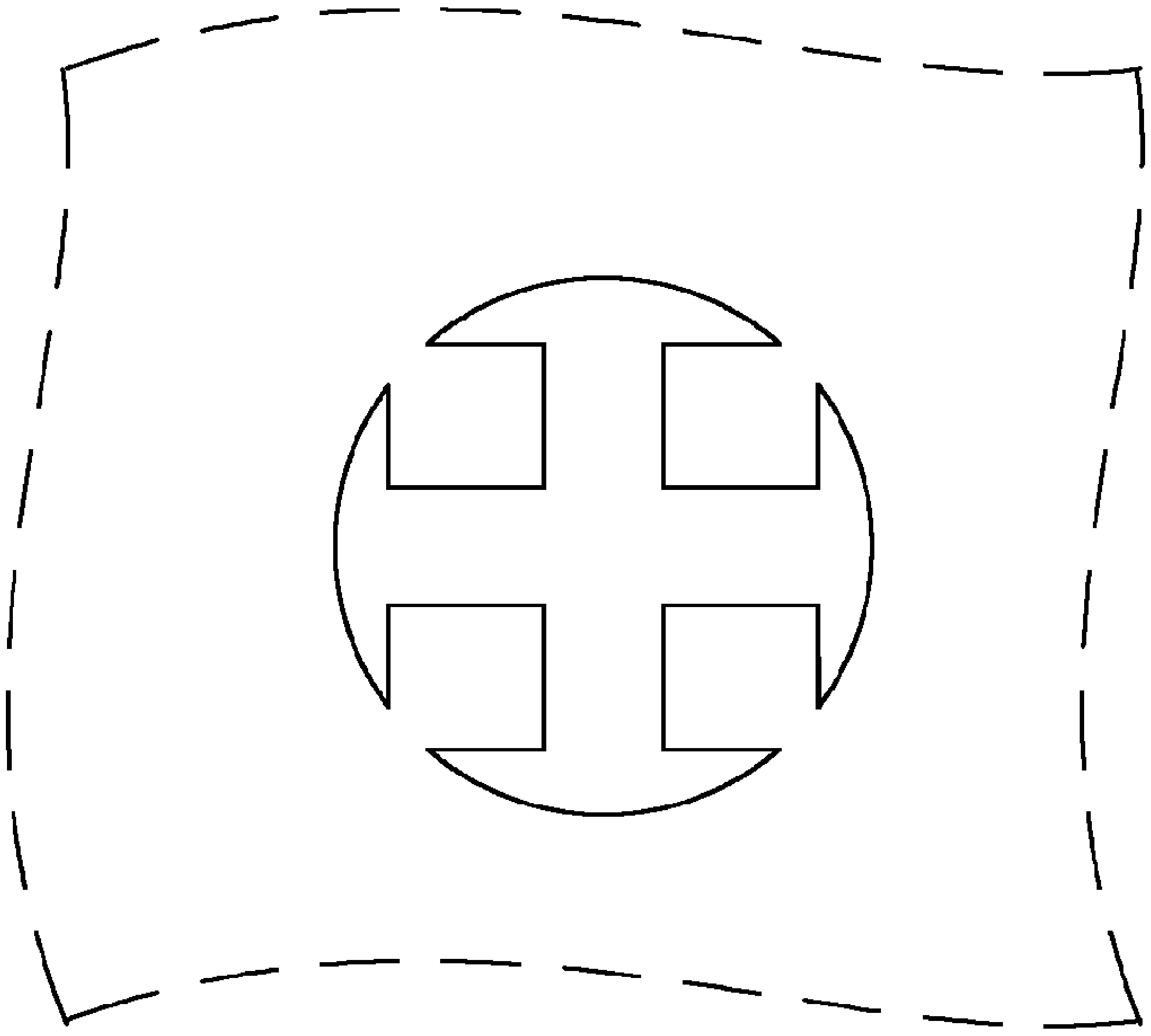

FIG. 11

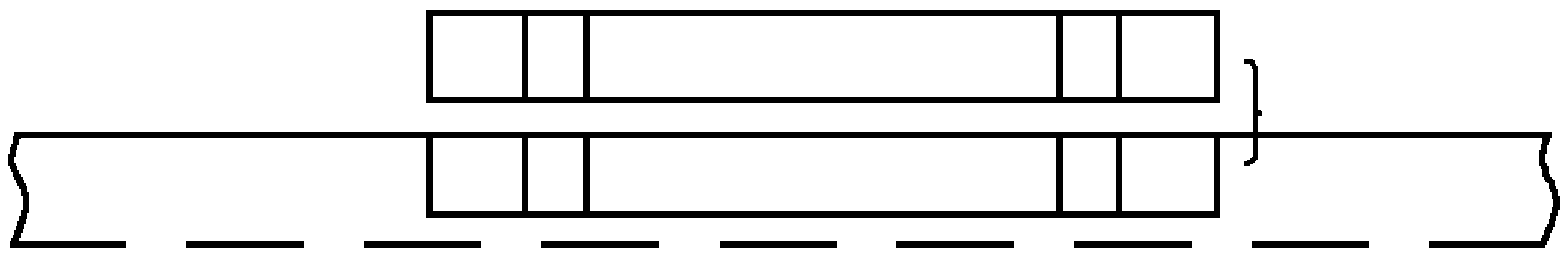

FIG. 12